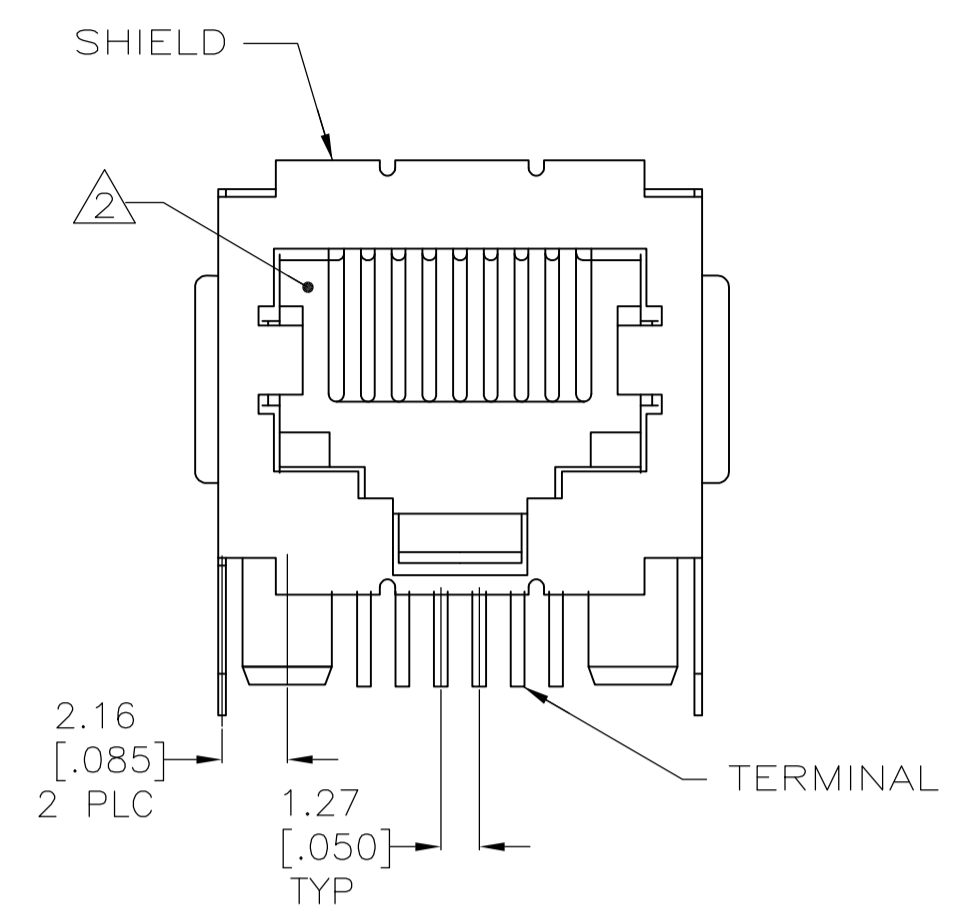
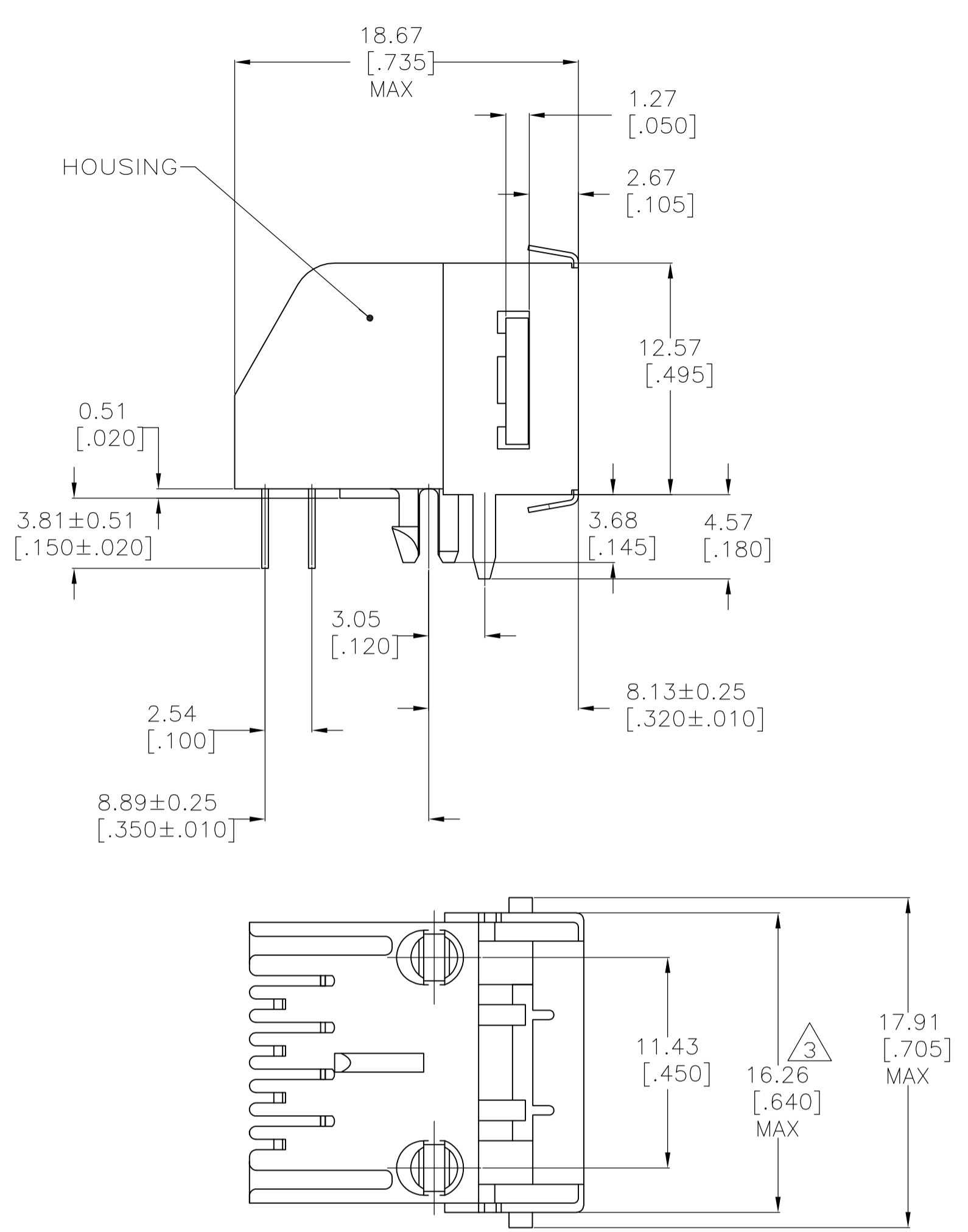
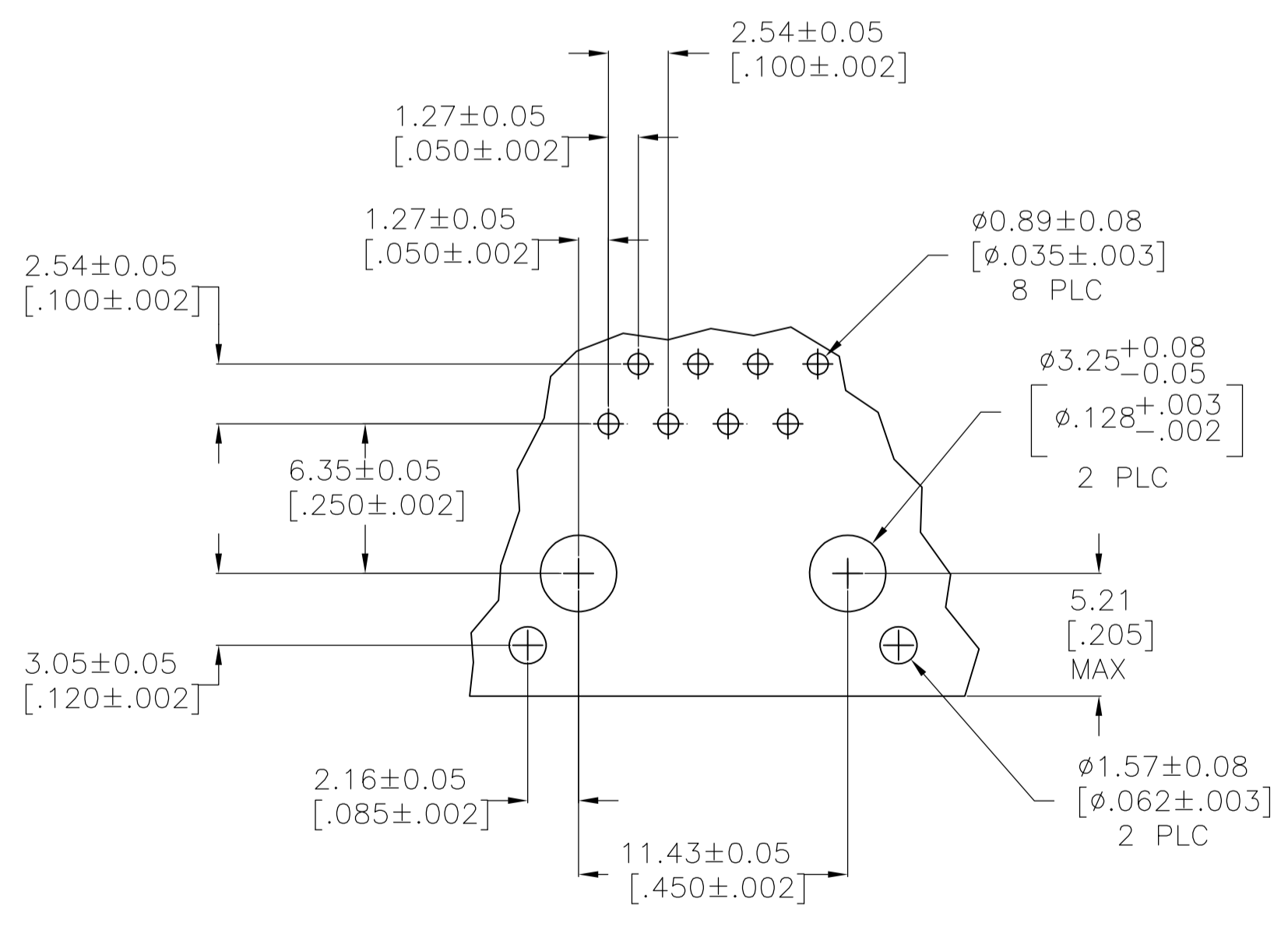


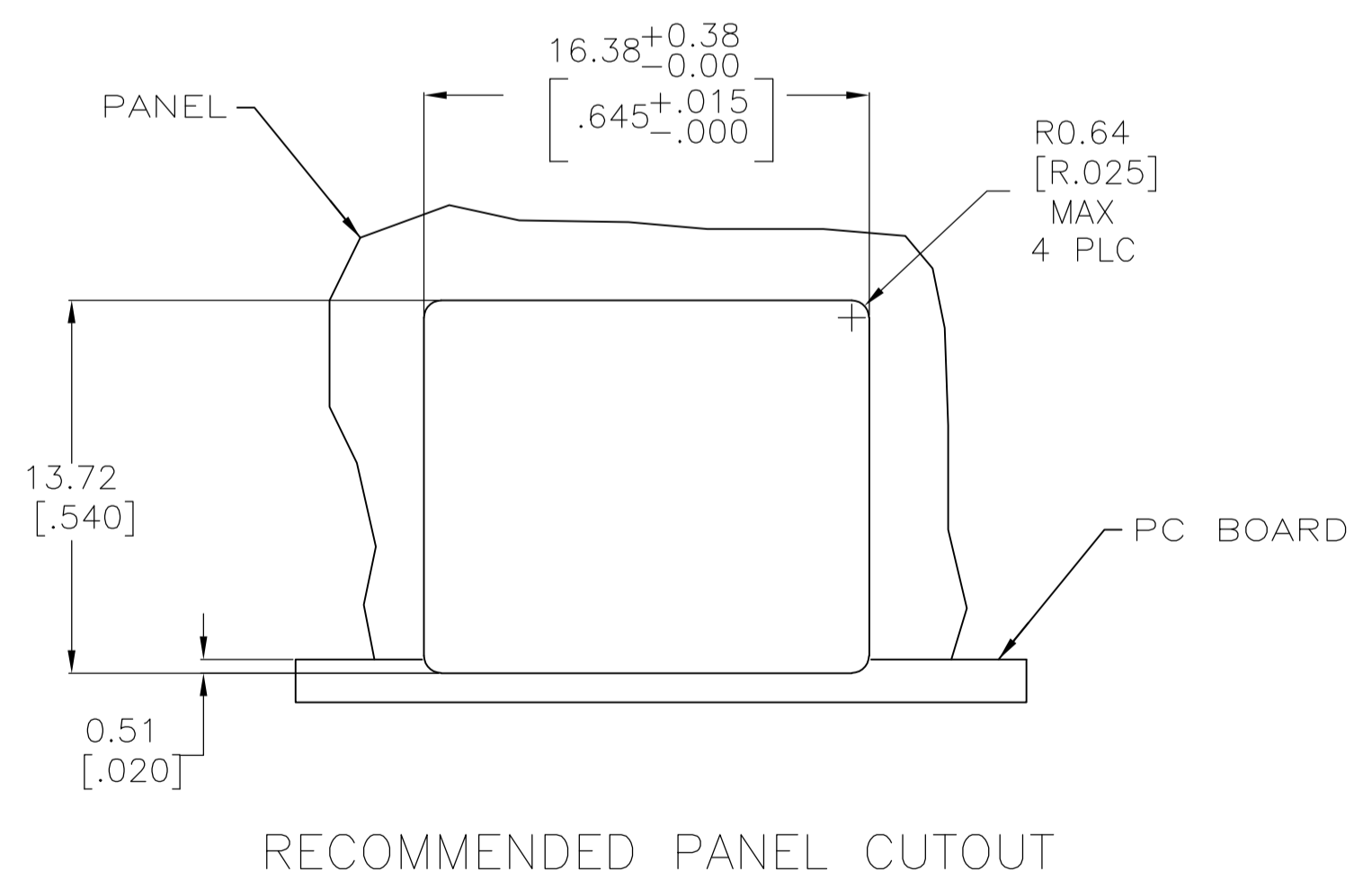
LOC		DIST		REVISIONS			
AA	00	REV	DATE	BY	CHK	APPV	
B1	REVISED PER ECO-11-005140		28MAR11	RK	HMR		



1. MATERIAL:  
 HOUSING (SEE TABLE) - COLOR: BLACK  
 TERMINAL - 0.36[.014] THICK PHOS BRONZE PLATED WITH 1.27 $\mu$ m [.000050] THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81 $\mu$ m [.000150] THICK MATTE TIN IN SOLDER AREA OVER 1.27 $\mu$ m [.000050] THICK NICKEL UNDERPLATE  
 SHIELD - 0.25 [.010] THICK COPPER ALLOY PLATED WITH 3.0 $\mu$ m [.000120] MINIMUM THICK REFLOWED TIN
- 2 CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- 3 DIMENSIONS MEASURED ALONG FRONT EDGES OF MATING FACE



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT (COMPONENT SIDE)



RECOMMENDED PANEL CUTOUT

YES	HIGH TEMP NYLON	5555141-3
NO	PBT POLYESTER	5555141-1
IR PROCESS COMPATIBLE	HOUSING MATERIAL	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm [INCHES]	TOLERANCES UNLESS OTHERWISE SPECIFIED:	DWG: G. GARRETT/L.A. MAYER	DATE: 04APR2005	 TE Connectivity
0 PLC ± -	1 PLC ± -	CHK: J. WESTMAN	DATE: 04APR2005	
1 PLC ± -	2 PLC ± 0.13[.005]	APPV: S. FLICKINGER	DATE: 04APR2005	NAME: MODULAR JACK ASSEMBLY, SHIELDED, 8 POSITION, LOW PROFILE, RIGHT ANGLE, PANEL GROUND WITH PANEL STOPS
2 PLC ± -	3 PLC ± -	PRODUCT SPEC: 108-1163	APPLICATION SPEC: 114-2048	SIZE: A1
3 PLC ± -	4 PLC ± -	WEIGHT: -	SCALE: 4:1	RESTRICTED TO: -
4 PLC ± -	ANGLES ± -	CUSTOMER DRAWING	SHEET: 1 OF 1	REV: B1

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)